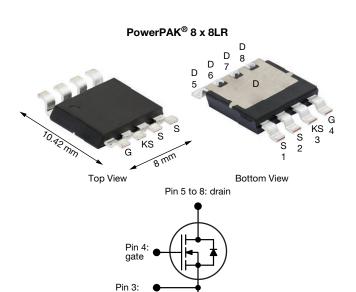
COMPLIANT

HALOGEN

FREE



E Series Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.074		
Q _g max. (nC)	63			
Q _{gs} (nC)	19			
Q _{gd} (nC)	10			
Configuration	Single			

Pin 1 to 2: source

N-Channel MOSFET

Kelvin connection

FEATURES

- 4th generation E series technology
- Low figure of merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8LR
Lead (Pb)-free and halogen-free	SiHR080N60E-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	600	W	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I _D	51	А	
	V _{GS} at 10 V	T _C = 100 °C		32		
Pulsed drain current ^a			I _{DM}	96	1	
Linear derating factor				4.0	W/°C	
Single pulse avalanche energy b			E _{AS}	173	mJ	
Maximum power dissipation			P _D	500	W	
Operating junction and storage temperature ra	ange		T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope		T _J = 125 °C	T _J = 125 °C 100		V/ns	
Reverse diode dv/dt ^d	de dv/dt ^d		dv/dt	10	V/IIS	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. $V_{DD} = 120 \text{ V}$, starting $T_J = 25 \,^{\circ}\text{C}$, $L = 28.2 \,\text{mH}$, $R_g = 25 \,\Omega$, $I_{AS} = 3.5 \,\text{A}$
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting T_J = 25 °C



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R_{thJA}	-	42	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	-	0.25	C/VV	

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.64	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	· V _{GS} , I _D = 250 μA	3.0	-	5.0	V
Onto anima lankana		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	V _{GS} = ± 30 V		-	± 1	μΑ
Zana mata waltana alusin awanat		$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	-	1	1 uA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	10	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 17 A	-	0.074	0.084	Ω
Forward transconductance a	9 _{fs}	V _{DS} = 20 V, I _D = 17 A		-	4.6	-	S
Dynamic		•					
Input capacitance	C _{iss}	V _{GS} = 0 V,		-	2557	-	pF
Output capacitance	C _{oss}	Π,	V _{GS} = 0 V, V _{DS} = 100 V,		105	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	6	-	
Effective output capacitance, energy related ^a	$C_{o(er)}$	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	79	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	499	-	
Total gate charge	Qg			-	42	63	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 17 \text{ A}, V_{DS} = 480 \text{ V}$		19	-	nC
Gate-drain charge	Q _{gd}				10	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 480 V, I _D = 17 A,		-	31	62	ns ns
Rise time	t _r			-	96	144	
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		37	74	
Fall time	t _f			-	31	62	
Gate input resistance	R_g		f = 1 MHz		0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	showing the	MOSFET symbol showing the		-	51	
Pulsed diode forward current	I _{SM}	integral reverse p - n junction diode		-	-	96	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 17 \text{ A},$ $di/dt = 80 \text{ A/µs}, V_R = 25 \text{ V}$		-	441	882	ns
Reverse recovery charge	Q _{rr}			-	5.2	10.4	μC
Reverse recovery current	I _{RRM}			_	21	_	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

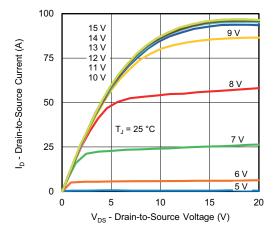


Fig. 1 - Typical Output Characteristics

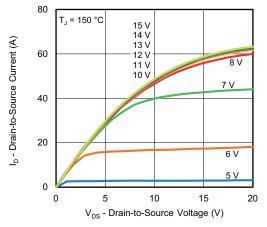


Fig. 2 - Typical Output Characteristics

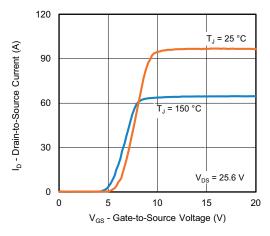


Fig. 3 - Typical Transfer Characteristics

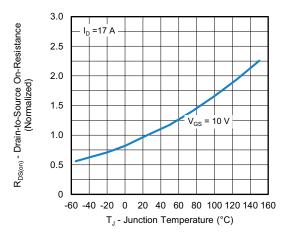


Fig. 4 - Normalized On-Resistance vs. Temperature

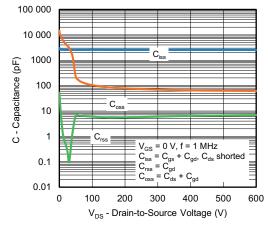


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

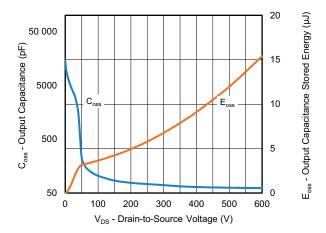


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



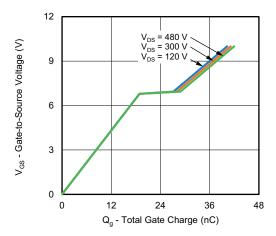


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

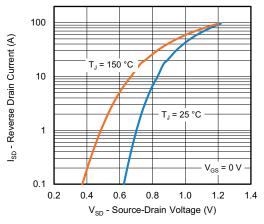


Fig. 8 - Typical Source-Drain Diode Forward Voltage

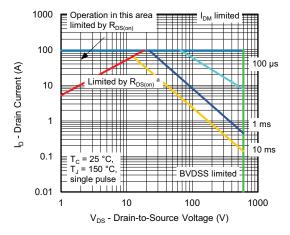


Fig. 9 - Maximum Safe Operating Area



a. $V_{GS} > minimum \ V_{GS}$ at which $R_{DS(on)}$ is specified

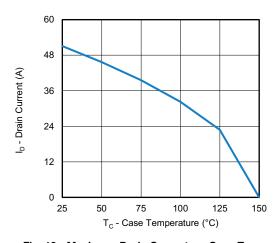


Fig. 10 - Maximum Drain Current vs. Case Temperature

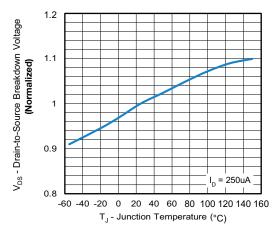


Fig. 11 - Temperature vs. Drain-to-Source Voltage



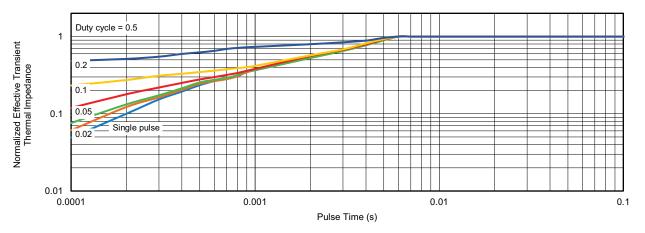


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

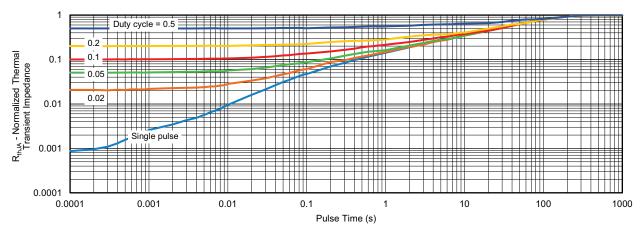


Fig. 13 - Normalized Transient Thermal Impedance, Junction-to-Ambient

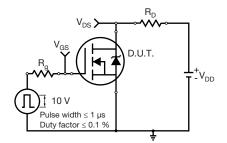


Fig. 14 - Switching Time Test Circuit

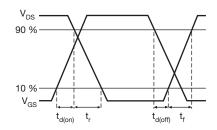


Fig. 15 - Switching Time Waveforms



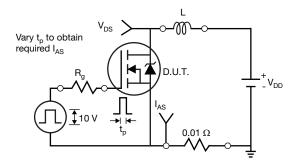


Fig. 16 - Unclamped Inductive Test Circuit

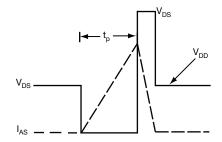


Fig. 17 - Unclamped Inductive Waveforms

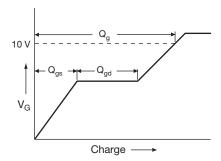


Fig. 18 - Basic Gate Charge Waveform

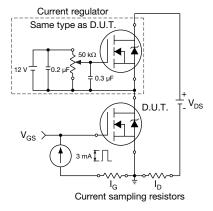


Fig. 19 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit

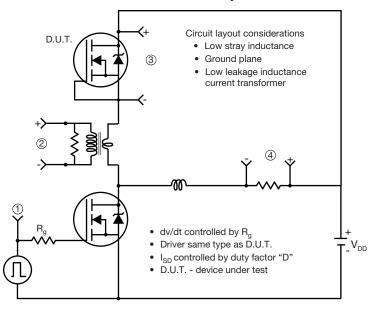




Fig. 20 - For N-Channel

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